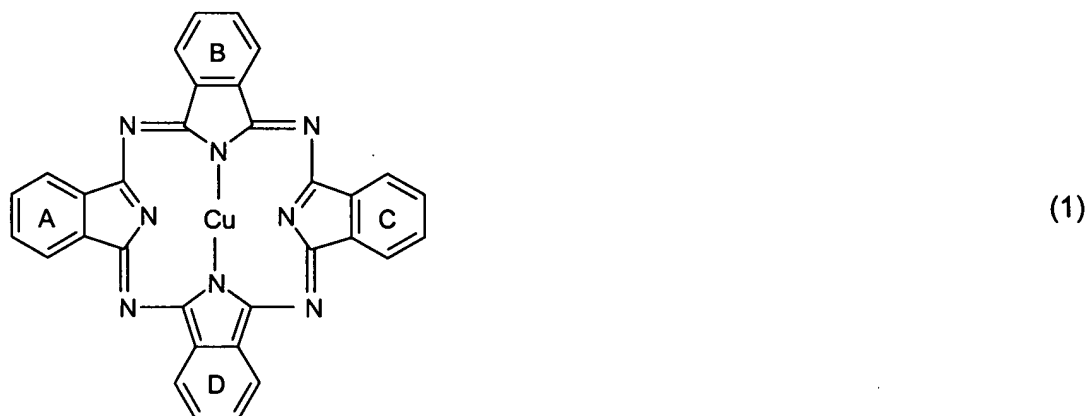



In the claims

1. **(currently amended):** A photosensitive resin composition comprising
as a component (A) a green colorant of the formula



in which the rings A, B, C and D are substituted by hydroxy or by the moiety $-O-(CR_1R_2)_n-$ ,

wherein R_1 is hydrogen or C_1-C_4 -Alkyl, R_2 is hydrogen or C_1-C_4 -Alkyl,

n is 0, 1, 2 or 3 and the ring E is unsubstituted or substituted by C_1-C_6 alkyl, C_1-C_6 alkoxy, hydroxy, $NHCO R_3$, $NHSO_2 R_4$ or $SO_2 NHR_5$, wherein R_3 is C_1-C_4 -Alkyl or phenyl, R_4 is C_1-C_4 -Alkyl or phenyl and R_5 is C_1-C_4 -Alkyl or phenyl,

b) as a component (B) an alkali soluble reactive or unreactive oligomer or reactive or unreactive polymer-~~(reactive or unreactive)~~,

c) as a component (C) a polymerizable monomer,

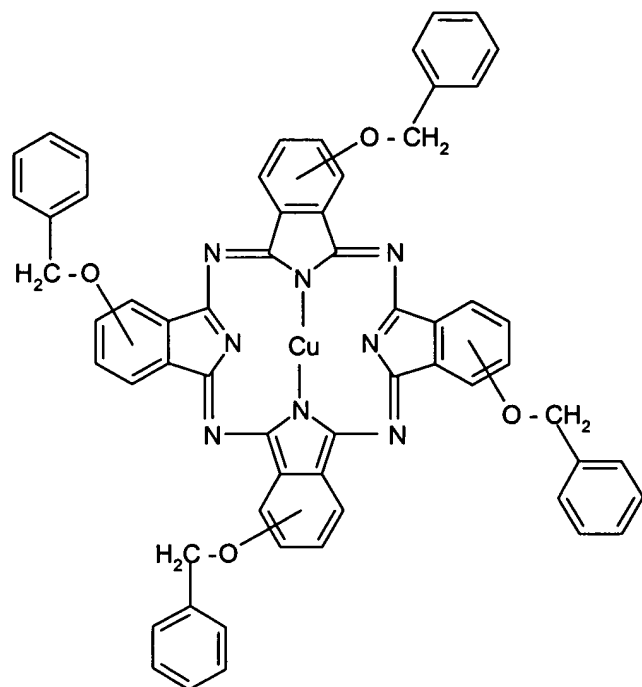
d) as a component (D) a photoinitiator,

e) as a component (E) an epoxy compound,

and also, if desired,

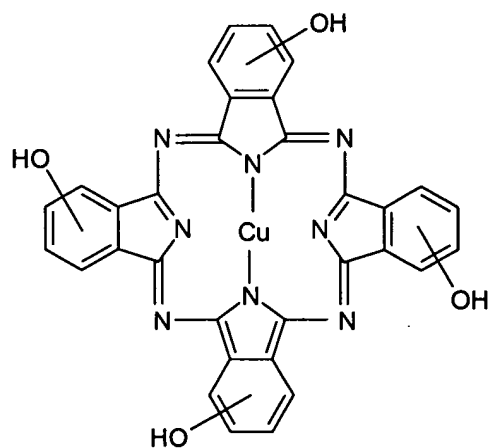
f) as a component (F) further additives.

2. **(original)**: A photosensitive resin composition according to claim 1, wherein the component (A) is the colorant of formula



(2).

3. **(original)**: A photosensitive resin composition according to claim 1, wherein the component (A) is the colorant of formula



(3).

4. (currently amended): Solder resist process, ~~using the photosensitive resin composition according to any one of claims 1 to 3,~~ which process comprises the steps of

(1) mixing the components (A) to (E) and if desired (F) according to claim 1,

(2) applying the resulting composition to the substrate ~~("coating of the substrate")~~ to generate a coated substrate,

(3) evaporating ~~of the solvent,~~ if present, at a temperature between 80-90°C,

(4) exposing the coated substrate to irradiation through a negative mask or by a direct laser imaging,

(5) developing the irradiated sample by washing with aqueous alkaline solution and thereby removing the uncured areas,

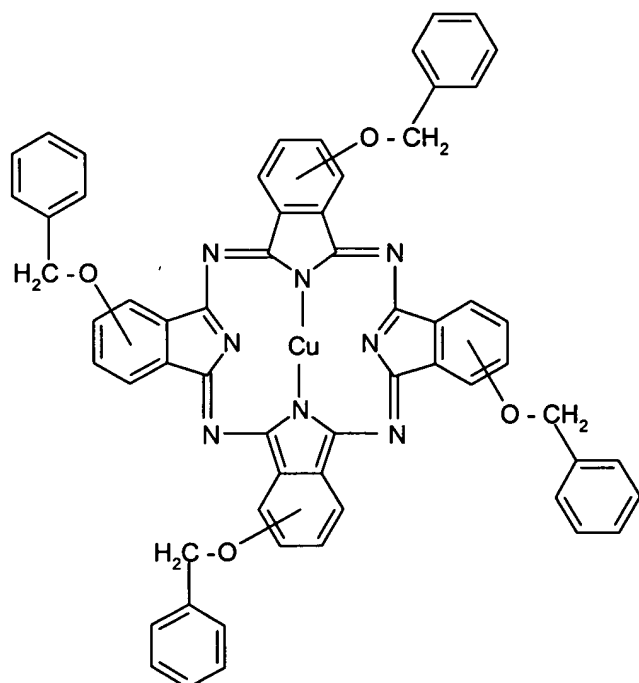
and

(6) thermally curing the sample at a temperature about 150°C, thereby initiating the crosslinking between the carboxylic acid and the epoxy component.

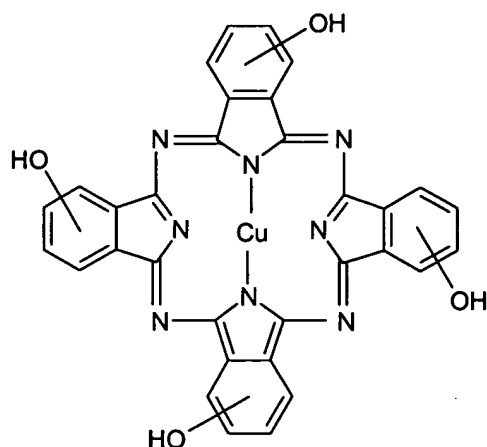
5. (original): Coated substrate obtained by the process according to claim 4.

6. (currently amended): Substrate coated with the photosensitive resin composition according to ~~any of claim [[s]] 1 to 3.~~

7. (new): Solder resist process according to claim 4, wherein component (A) of step (1) is the colorant of formula



8. (new): Solder resist process according to claim 4, wherein component (A) of step (1)) is the colorant of formula



9. (new): Coated substrate obtained by the process according to claim 7.

10. (new): Coated substrate obtained by the process according to claim 8.

11. (new): Substrate coated with the photosensitive resin composition according to claim 2.

12. (new): Substrate coated with the photosensitive resin composition according to claim 3.

**This Page is Inserted by IFW Indexing and Scanning
Operations and is not part of the Official Record**

BEST AVAILABLE IMAGES

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images include but are not limited to the items checked:

- ☐ **BLACK BORDERS**
- ☐ **IMAGE CUT OFF AT TOP, BOTTOM OR SIDES**
- ☐ **FADED TEXT OR DRAWING**
- ☐ **BLURRED OR ILLEGIBLE TEXT OR DRAWING**
- ☐ **SKEWED/SLANTED IMAGES**
- ☐ **COLOR OR BLACK AND WHITE PHOTOGRAPHS**
- ☐ **GRAY SCALE DOCUMENTS**
- ☐ **LINES OR MARKS ON ORIGINAL DOCUMENT**
- ☐ **REFERENCE(S) OR EXHIBIT(S) SUBMITTED ARE POOR QUALITY**
- ☐ **OTHER:** _____

IMAGES ARE BEST AVAILABLE COPY.

As rescanning these documents will not correct the image problems checked, please do not report these problems to the IFW Image Problem Mailbox.